

Release Notes DA1469x SDK SW-B-001

Abstract

This document contains the release notes for Dialog Semiconductor's DA1469x Software Development Kit, version 10.0.6.90



Contents

Αb	stract			. 1
1	Term	s and De	finitions	. 5
2	Release Data			. 5
3	License			. 5
4	Related Documentation and References			. 5
5	Relea	se Desci	ription	. 6
	5.1		V	
	5.2	Fixes an	d Improvements since 10.0.6.88	. 6
	5.3 Known Issues of 10.0.6.90			. 6
	5.4	Known L	imitations of 10.0.6.90	. 6
6	Relea	se Histo	ry	. 7
	6.1		10.0.6.88	
		6.1.1	Overview	. 7
		6.1.2	New and Updated Features of 10.0.6.88	. 7
		6.1.3	Fixes and Improvements since 10.0.4.66.2	. 7
		6.1.4	Known Issues and Limitations of 10.0.6.88	. 8
	6.2	Version '	10.0.4.66.2	. 9
		6.2.1	Overview	. 9
		6.2.2	New and Updated Features of 10.0.4.66.2	. 9
		6.2.3	Fixes and Improvements since 10.0.4.66.1	. 9
		6.2.4	Known Issues and Limitations of 10.0.4.66.2	
	6.3		10.0.4.66.1	10
		6.3.1	Overview	
		6.3.2	New and Updated Features of 10.0.4.66.1	
		6.3.3	Fixes and Improvements since 10.0.4.66	
		6.3.4	Known Issues and Limitations of 10.0.4.66.1	
	6.4		10.0.4.66	
		6.4.1	Overview	
		6.4.2	New and Updated Features of 10.0.4.66	
		6.4.3	Fixes and Improvements since 10.0.2.60	
		6.4.4	Known Issues and Limitations of 10.0.4.66	
	6.5		10.0.2.60	. •
		6.5.1	Overview	
		6.5.2	New and Updated Features of 10.0.2.60	
		6.5.3 6.5.4	Fixes and Improvements since 10.0.1.52	
	6.6		10.0.1.52	
	0.0	6.6.1	Overview	
		6.6.2	New and Updated Features of 10.0.1.52	
		6.6.3	Fixes and Improvements since 10.0.1.39	
		6.6.4	Known Issues and Limitations of 10.0.1.52	
	6.7		10.0.1.39	
	J.,	6.7.1	Overview	
				-



	6.7.2	New and Updated Features of 10.0.1.39	10
	6.7.3	Fixes and Improvements since 10.0.1.32	16
	6.7.4	Known Issues and Limitations of 10.0.1.39	16
6.8	Version	10.0.1.32	18
	6.8.1	Overview	18
	6.8.2	New and Updated Features of 10.0.1.32	18
	6.8.3	Fixes and Improvements since 10.0.1.28	
	6.8.4	Known Issues and Limitations of 10.0.1.32	
6.9		10.0.1.28	
0.0	6.9.1	Overview	
	6.9.2	New and Updated Features of 10.0.1.28	
	6.9.3	Fixes and Improvements since 10.0.1.16	
	6.9.4	Known Issues and Limitations of 10.0.1.28	
0.40			
6.10		10.0.1.16	
	6.10.1	Overview	
	6.10.2	New and Updated Features of 10.0.1.16	
	6.10.3	Known Issues and Limitations of 10.0.1.16	
Appendi	x A Softw	ware Versioning Rules	24
Docume	nt Revisi	ion History	25
Tables			
Tables	5		
		on Table	
		Fixes and Improvements	
		Known Issues Known Limitations	
		New Features	
		Fixes and Improvements	
		Known Issues	
		5.2 New Features	
		6.2 Fixes and Improvements	
		6.1 New Features	
		6.1 Fixes and Improvements	
		6.1 Known Issues	
		6 New Features	
		6 Known Issues	
Table 18:	: 10.0.2.60	0 New Features	13
		0 Fixes and Improvements	
		0 Known Issues	
Table 21:		O Nov. Footures	4 /
		2 New Features	
Table 22:	: 10.0.1.52	2 New Features	14
Table 22: Table 23: Table 24:	: 10.0.1.52 : 10.0.1.52 : 10.0.1.39	2 Fixes and Improvements	14 15 16
Table 22: Table 23: Table 24: Table 25:	: 10.0.1.52 : 10.0.1.52 : 10.0.1.39 : 10.0.1.39	2 Fixes and Improvements	14 15 16
Table 22: Table 23: Table 24: Table 25: Table 26:	: 10.0.1.52 : 10.0.1.52 : 10.0.1.39 : 10.0.1.39 : 10.0.1.39	2 Fixes and Improvements	14 15 16 16
Table 22: Table 23: Table 24: Table 25: Table 26: Table 27:	: 10.0.1.52 : 10.0.1.52 : 10.0.1.39 : 10.0.1.39 : 10.0.1.39 : 10.0.1.32	2 Fixes and Improvements 2 Known Issues 9 New Features 9 Fixes and Improvements 9 Known Issues 2 New Features	14 15 16 16 18
Table 22: Table 23: Table 24: Table 25: Table 26: Table 27: Table 28: Table 29:	: 10.0.1.5; : 10.0.1.5; : 10.0.1.3; : 10.0.1.3; : 10.0.1.3; : 10.0.1.3; : 10.0.1.3;	2 Fixes and Improvements 2 Known Issues 9 New Features 9 Fixes and Improvements 9 Known Issues 2 New Features 2 Fixes and Improvements	14 15 16 16 18 18
Table 22: Table 23: Table 24: Table 25: Table 26: Table 27: Table 28: Table 29: Table 30:	: 10.0.1.5; : 10.0.1.5; : 10.0.1.39; : 10.0.1.39; : 10.0.1.39; : 10.0.1.3; : 10.0.1.3; : 10.0.1.3;	2 Fixes and Improvements 2 Known Issues 9 New Features 9 Fixes and Improvements 9 Known Issues 2 New Features 2 Fixes and Improvements	14 15 16 16 18 18 18

SW-B-001001



DA1469x SDK

Table 32: 10.0.1.28 Known Issues	2
Table 33: 10.0.1.16 New Features	22
Table 34: 10.0.1.16 Known Issues	2



DA1469x SDK

1 Terms and Definitions

GA General access
LA Limited access

BLE Bluetooth Low Energy

DMA Direct Memory Access

SDK Software Development Kit

FPGA Field Programmable Gate Array

SUOTA Software Update Over The Air

TRNG True Random Number Generator

OTP One Time Programmable memory

TX Transmit

NVMS Non Volatile Memory Storage

IRQ Interrupt Request

FW Firmware

API Application Programming Interface

USB Universal Serial Bus SNC Sensor Node Controller OS Operating System

2 Release Data

Table 1: Information Table

Software	SDK10 (DA1469x SDK)
Device Number	DA14691, DA14695, DA14697, DA14699
Software Release Date	27 September 2019
Software Version Number	10.0.6.90
Software Release Type (Note 1)	FULL (GA)

Note 1 Releases can be of the following types: FULL (GA), FULL (LA), RELEASE CANDIDATE, ENGINEERING, PATCH or BINARY

3 License

Licenses covering this SDK release are listed in the license.txt file in SDK doc folder.

4 Related Documentation and References

- [1] UM-B-090, DA1469x Getting Started with the Development Kit, Revision 2.0, User Manual, Dialog Semiconductor.
- [2] UM-B-092, DA1469x Software Platform Reference, Revision 4.0, User Manual, Dialog Semiconductor.



DA1469x SDK

5 Release Description

5.1 Overview

This is a full release of SDK 10.0.6 which supports the DA1469x device. It adds support in the OTP configuration script for XTAL trim values and BD address.

5.2 Fixes and Improvements since 10.0.6.88

Table 2: 10.0.6.90 Fixes and Improvements

Fix Number	Description
0066/01	Support XTAL32M trim settings from OTP Configuration Script
0090.02	Bluetooth BD Address can be stored in OTP Configuration Script

5.3 Known Issues of 10.0.6.90

Table 3: 10.0.6.90 Known Issues

Issue Number	Description
0088.01	When RCX is used as an LP clock, the RTC is not compensated according to the calculated frequency of the RCX.
0066.02	Assertion will hit during USB suspend/resume if reset is received before resume
0028.04	Detaching from Eclipse Debugger is not always successful

5.4 Known Limitations of 10.0.6.90

Table 4: 10.0.6.90 Known Limitations

Issue Number	Description
0088.02	After system reset the same Private Random Resolvable Address is generated
0016.10	Watchpoints not yet supported by Segger debugger



6 Release History

6.1 Version 10.0.6.88

Version 10.0.4.88 of SDK was released on August 2nd, 2019

6.1.1 Overview

This is a full release (Note 1) of 10.0.6 SDK that runs on the DA1469x devices. It can be used for application development, testing and production.

6.1.2 New and Updated Features of 10.0.6.88

Table 5: 10.0.6.88 New Features

Feature Number	Description
320_03	Added support for using RCX as low power clock
322_03	Added API for controlling radio TX power
114_07	Added support for BLE (CMAC) reset

6.1.3 Fixes and Improvements since 10.0.4.66.2

Table 6: 10.0.6.88 Fixes and Improvements

Fix Number	Description
0088/01	Added ble_cli demo project
0088/02	Added mtb contents in memory dump (collect_debug_info script)
0088/03	Use same ccc value length (2) in all services
0088/04	Upgrade to CMSIS v5.5.1
0088/05	Improve power consumption by dynamically adjusting the level of the V12 rail.
0088/06	Improve the measurements for all the GPADC temperature channels using empirical calibration data.
0088/07	Extend the Stack Pointer (SP) range check in HardFault_Handler() taking into account the PSRAM presence.
0088/08	Allow user to explicitly issue an I2C RESTART regardless of whether or not the transfer direction is changing.
0088/09	Add flow control to BLE security requests
0088/10	Improve hogp_host by being able to provide the connection id as user input
0088/11	Handle improper BD address user input in ble_multi_link project
0088/12	Update the register CMSIS files to match the datasheet description
0088/13	Fixed image flashing using Toolbox
0088/14	Fixed charger's EoC current threshold values (align with chip characterization data)
0088/15	Fixed overflow in portCONVERT_MS_2_TICKS, portCONVERT_TICKS_2_MS macro calculations for timer values over 4.295 seconds (at a typical tick-rate of 1KHz).
0088/16	Fixed low level driver hw_smotor_get_fifo_command(uint8_t index) API reading of Step Motor Controller FIFO contents
0088/17	Fixed double issuing of flash power down command when entering extended sleep
0088/18	Fixed bus-fault upon re-configuration of SDADC adapter when HW_SDADC_VREF_INTERNAL is used as vref_voltage



Fix Number	Description
0088/19	Fixed check for active PLL in Power Management Unit low level driver when shutting down 1V4 rail is requested
0088/20	Fixed race condition in DMA configuration resulting in clearing DMA INT enable
0088/21	Fixed the procedure for detecting the VBUS state (attach or detach).
0088/22	Fixed overflow when converting XTAL32M Ready IRQ counter cycles to LP clock cycles
0088/23	Fixed misconfiguration of LRA haptic block improving driving performance
0088/24	Fixed hw_i2c_write_buffer_sync() to block until all bytes have been transmitted.
0088/25	Fixed not being able to start advertising for a 2nd time when a PRIVATE_RANDOM_RESOLVABLE_ADDRESS address is used.
0088/26	Fixed not being able for an application to get a BLE_EVT_GAP_CONNECTED event, if a disconnection happens while the address resolution is in progress.
0088/27	Fixed a pending update request for one connection preventing a new update procedure on another.
0088/28	Fixed hw_timer_configure_pwm() not enabling correctly the TIMER and TIMER2 PWM output pin during sleep.
0088/29	Fixed clock configuration in SNC I2C driver in order to support a transaction with high speed configuration.
0066.03	Fixed issue with L2CAP start fragments with length < 4 bytes

6.1.4 Known Issues and Limitations of 10.0.6.88

Table 7: 10.0.6.88 Known Issues

Issue Number	Description
0088.01	When RCX is used as an LP clock, the RTC is not compensated according to the calculated frequency of the RCX.
0088.02	After system reset the same Private Random Resolvable Address is generated
0066.01	OTP XTAL trim values get overwritten by default values
0066.02	Assertion will hit during USB suspend/resume if reset is received before resume
0028.04	Detaching from Eclipse Debugger is not always successful
0016.10	Watchpoints not yet supported by Segger debugger



DA1469x SDK

6.2 Version 10.0.4.66.2

Version 10.0.4.66.2 of SDK was released on April 24th, 2019

6.2.1 Overview

This was a full release of 10.0.4 SDK, which added support for the DA1469x device. It can be used for application development, testing and production. This release included source code labelling corrections and updates.

6.2.2 New and Updated Features of 10.0.4.66.2

Table 8: 10.0.4.66.2 New Features

Feature Number	Description
-	No new features were added in this release

6.2.3 Fixes and Improvements since 10.0.4.66.1

Table 9: 10.0.4.66.2 Fixes and Improvements

Fix Number	Description
0066.2/01	Added workaround for errata issue 304 ("PLL calibration does not work properly")

6.2.4 Known Issues and Limitations of 10.0.4.66.2

Table 10: 10.0.4.66.2 Known Issues

Issue Number	Description
0066.01	OTP XTAL trim values get overwritten by default values
0066.02	Assertion will hit during USB suspend/resume if reset is received before resume
0066.03	L2CAP start fragments with length < 4 bytes will be ignored
0028.04	Detaching from Eclipse Debugger is not always successful
0016.10	Watchpoints not yet supported by Segger debugger



DA1469x SDK

6.3 Version 10.0.4.66.1

Version 10.0.4.66.1 of SDK was released on April 17th, 2019.

6.3.1 Overview

This was a full release of 10.0.4 SDK, which added support for the DA1469x device. It can be used for application development, testing and production. This release included source code labelling corrections and updates.

6.3.2 New and Updated Features of 10.0.4.66.1

Table 11: 10.0.4.66.1 New Features

Feature Number	Description
-	No new features were added in this release

6.3.3 Fixes and Improvements since 10.0.4.66

Table 12: 10.0.4.66.1 Fixes and Improvements

Fix Number	Description
0066.1/01	Source code labelling corrections and updates
0066.1/02	Remove obsolete SD-ADC clock selection option HW_SDADC_CLOCK

6.3.4 Known Issues and Limitations of 10.0.4.66.1

Table 13: 10.0.4.66.1 Known Issues

Issue Number	Description
0066.01	OTP XTAL trim values get overwritten by default values
0066.02	Assertion will hit during USB suspend/resume if reset is received before resume
0066.03	L2CAP start fragments with length < 4 bytes will be ignored
0028.04	Detaching from Eclipse Debugger is not always successful
0016.10	Watchpoints not yet supported by Segger debugger



6.4 Version 10.0.4.66

Version 10.0.4.66 of SDK was released on February 22nd, 2019.

6.4.1 Overview

This was a full release of 10.0.4 SDK, which added support for the DA1469x device. It can be used for application development, testing and production. This release included a number of fixes and improvements, as listed below.

6.4.2 New and Updated Features of 10.0.4.66

Table 14: 10.0.4.66 New Features

Feature Number	Description
-	No new features were added in this release

6.4.3 Fixes and Improvements since 10.0.2.60

Table 15: 10.0.4.66 Fixes and Improvements

Fix Number	Description
0066/01	Added support for USB Development Kit
0066/02	Support maximum image size loading over serial boot (128Kb)
0066/03	Fix unhandled pending read event in uart adapter
0066/04	Fix PM sleep_mode handling
0066/05	Fix handling of charging events on sys_charger
0066/06	Fix GPADC channel enumeration
0066/07	Fix cscp heap issues
0066/08	Fix waiting forever in I2C adapter forced close
0066/09	Fix BLE_EVT_GAP_DATA_LENGTH_SET_FAILED event in ble/mgr/gap
0066/10	Improved robustness of BLE controller
0066/11	Remove -wnocpp compilation flag from projects
0066/12	Fix static code analysis errors
0066/13	Fix endianess issue when writting to OTP from Toolbox
0066/14	Fix qspi_is_valid_addr() to execute from RAM
0066/15	Fix possible race condition in sdadc/uart drivers
0066/16	Fix wake up from K1 in hrp_sensor
0066/17	Fix secure SUOTA failures with CRC mismatch
0066/18	Add sleep support in DGTL
0066/19	Fix unregistering interrupt callback when force closing slave in I2C adapter
0066/20	Fix gpio power configuration in I2C/SPI/LCD adapters
0066/21	Add program_qspi_nvparam launcher
0066/22	Add support for FreeRTOS thread aware debugging in eclipse
0066/23	Add protection for race condition on XTAL32M_CTRL0_REG
0066/24	Fix cache configuration errors
0066/25	Refactor cache initialization



Fix Number	Description
0066/26	Add check for LDO_PLL_OK signal before enabling PLL
0066/27	Fix VDD voltage (0.828V) in hibernation mode
0066/28	Fix not protecting ble_storage_remove() functions
0066/29	Add API to retrieve low level stats in BLE adapter
0066/30	Fix issue while changing properties permission of BLE characteristics

6.4.4 Known Issues and Limitations of 10.0.4.66

Table 16: 10.0.4.66 Known Issues

Issue Number	Description
0066.01	OTP XTAL trim values get overwritten by default values
0066.02	Assertion will hit during USB suspend/resume if reset is received before resume
0066.03	L2CAP start fragments with length < 4 bytes will be ignored
0028.04	Detaching from Eclipse Debugger is not always successful
0016.10	Watchpoints not yet supported by Segger debugger



6.5 Version 10.0.2.60

Version 10.0.2.60 of SDK was released on Januart 14th, 2019.

6.5.1 Overview

This was a full release of 10.0.2 SDK, which added support for the DA1469x device. It can be used for application development, testing and production. This release included a number of fixes and improvements, as listed below.

6.5.2 New and Updated Features of 10.0.2.60

Table 17: 10.0.2.60 New Features

Feature Number	Description
912_02	Refactored Peripheral Adapters API
322_01	Updated radio driver

6.5.3 Fixes and Improvements since 10.0.1.52

Table 18: 10.0.2.60 Fixes and Improvements

Fix Number	Description
0060/01	Set default Vdd to 1V2
0060/02	Added automatic BLE security key renewal for DA1469x
0060/03	Added support for Uart 3 in UART adapter
0060/04	Added SDADC adapter
0060/05	Enable static GPIO power configuration support when SNC is used
0060/06	Added create flash image python script
0060/07	Fixed OSAL calls depending on execution context (simple task or ISR)
0060/08	Support BLE 2Mbit high performance radio mode
0060/09	Improved robusteness of BLE controller / host
0060/10	Use HW_SPI_FIFO_RX_TX in spi adapter write calls
0028.09	SDK uses TRNG for generating random numbers
0028.07	Bond Management Service (BMS) example gives a new random key after reset
0052.01	Added support for SCA and other BLE parameters in NVPARAMS

6.5.4 Known Issues and Limitations of 10.0.2.60

Table 19: 10.0.2.60 Known Issues

Issue Number	Description
0060.01	Removed plt_fw project from release files
0028.04	Detaching from Eclipse Debugger is not always successful.
0028.06	Parameter Update sometimes fails with LMP LL Response Timeout.
0016.10	Watchpoints not yet supported by Segger debugger.



6.6 Version 10.0.1.52

Version 10.0.1.52 of SDK was released on December 7th, 2018.

6.6.1 Overview

This was an engineering release of 10.0.1 SDK, which added support for the DA1469x device. It can be used for application development and testing.

Dialog will make every effort to maintain API compatibility. However, developed code may have to be ported to run on the official SDK release once that becomes available.

This release included a number of fixes and improvements, as well as a number of new features, as listed below.

6.6.2 New and Updated Features of 10.0.1.52

Table 20: 10.0.1.52 New Features

Feature Number	Description
131_02	AMS Client Profile
120_14	HID Service
130_14	CSCP 1.0: Cycling Speed and Cadence Profile - Collector
510_08	Micro Trace Buffer support
450_04	Support USB charging, including enumeration
440_01	CDC serial over USB
440_03	MSD over USB
420_04	Added security framework for AES/Hash/ECC/TRNG algorithms

6.6.3 Fixes and Improvements since 10.0.1.39

Table 21: 10.0.1.52 Fixes and Improvements

Fix Number	Description
0028.03	SUOTA stability issues have been observed with stress tests.
0028.05	Removed unneeded clock pulses after byte read command in SPI adapter.
0031.02	Improved stability of pxp_reporter application under stress testing.
0031.04	Improved robustness in ble_multi_link application.
0039.02	Sleep is now blocked while a DMA transfer is in progress
0039.03	Fixed transaction abort issue in Sensor Node Controller driver for I2C
0052/01	Improved robustness of BLE Controller & Host
0052/02	Updated Power and clock management for stability
0052/03	Updated NMVS to add power-safety
0052/04	Improved radio performance
0052/05	Added a board abstraction layer
0052/06	Refactored USB Framework
0052/07	Added support for external OSC as LP clock
0052/08	Extend & refactor SENIS API
0052/09	Support USB suspend/resume



Fix Number	Description
0052/10	Extend ERM driver API
0052/11	Add suppport for JLink Flashing tool
0052/12	Add support for secure boot in python scripts
0052/13	Restore GPADC configuration after sleep
0052/14	plt_fw: Fix code location in custom_config_ram
0052/15	aes_hash: Add support for reading keys form OTP
0052/16	Support new 4MB flash partition layout

6.6.4 Known Issues and Limitations of 10.0.1.52

Table 22: 10.0.1.52 Known Issues

Issue Number	Description
0052.01	Sleep clock accuracy can only be configured complile time, not through NVMS
0028.04	Detaching from Eclipse Debugger is not always successful.
0028.06	Parameter Update sometimes fails with LMP LL Response Timeout.
0028.07	Bond Management Service (BMS) example gives the same pin key after reset.
0028.09	TRNG is not used by the SDK for generating random numbers.
0016.10	Watchpoints not yet supported by Segger debugger.



6.7 Version 10.0.1.39

Version 10.0.1.39 of SDK was released on September 28th, 2018.

6.7.1 Overview

This was an engineering release of 10.0.1 SDK, which added support for the DA1469x device. It can be used for application development and functional testing. It is not yet fully evaluated and it cannot be used for testing final products.

Dialog will make every effort to maintain API compatibility. However, developed code may have to be ported to the official SDK release once that becomes available.

It included code for low level access to the LRA and Motrol Controller peripherals, moves to the GCC v7 and improves overall maturity.

6.7.2 New and Updated Features of 10.0.1.39

Table 23: 10.0.1.39 New Features

Feature Number	Description
112_04	Support for Channel Selection Algorithm #2
328_01	Initial implementation of a low level driver for LRA
328_06	Initial implementation of a low level driver fo Motor Controller
460_03	QSPI Flash/RAM Adapter
510_02	Upgrade to GNU/GCC version 7

6.7.3 Fixes and Improvements since 10.0.1.32

Table 24: 10.0.1.39 Fixes and Improvements

Fix Number	Description
0031.01	Configuration option allows to select TX power of 0dB or 6dB for a project
0031.03	Increased application stability seen in stress tests.
0016.04	Cleanup of release files to minimise references to DA1468x SDK.
0016.05	Restructured Doxygen documentation
0016.09	Added calibration support for values returned by the GPADC driver.
0039/01	Improved RSSI read command
0039/02	Upgraded to latest version of BLE Stack Library
0039/03	Enable reading configuration data from OTP as default.
0039/04	Restructured SDK folders
0039/05	Fixed high speed transaction issue in SNC i2c driver

6.7.4 Known Issues and Limitations of 10.0.1.39

Table 25: 10.0.1.39 Known Issues

Issue Number	Description
0039.01	Qspi LLD Api changed to support QSPI2 interface (impacts backwards compatibility)
0039.02	Sleep is not blocked while a DMA transfer is in progress.
0039.03	Issue in Sensor Node Controller driver for I2C with transaction abort.



Issue Number	Description
0031.02	pxp_reporter application stability issues have been observed in stress tests.
0031.04	ble_multi_link application sometimes fail to report device disconnection.
0028.01	Charger configuration is only tested with wall plug adapters at room temperature.
0028.03	SUOTA stability issues have been observed with stress tests.
0028.04	Detaching from Eclipse Debugger is not always successful.
0028.05	SPI adapter creates unneeded clock pulses after byte read command.
0028.06	Parameter Update sometimes fails with LMP LL Response Timeout.
0028.07	Bond Management Service (BMS) example gives the same pin key after reset.
0028.09	TRNG is not used by the SDK for generating random numbers.
0016.10	Watchpoint support for debugging is not included.



6.8 Version 10.0.1.32

Version 10.0.1.32 of SDK was released on May 25th, 2018.

6.8.1 Overview

This was an engineering release of 10.0.1 SDK, which added support for the DA1469x device. It can be used for application development and functional testing. It is not yet fully evaluated and it cannot be used for testing final products.

Dialog will make every effort to maintain API compatibility. However, developed code may have to be ported to the official SDK release once that becomes available.

It included more BLE examples, moves to the latest FreeRTOS v10.0.1 and improves overall maturity. A detailed list of new features is given below.

6.8.2 New and Updated Features of 10.0.1.32

Table 26: 10.0.1.32 New Features

Feature Number	Description
111_04	Efficient non connectable advertising – CSSv6
111_01	LE Secure Connection
112_05	High duty cycle non connectable advertising
114_01	Multilink support
400_01	Update to FreeRTOS 10.0.1
120_09	CSCS 1.0: Cycling Speed and Cadence Profile
130_24	HRP 1.0:: Heart Rate Profile - Collector
130_21	HOGP 1.0: HID Over GATT Profile - HID Device
130_22	HOGP 1.0: HID Over GATT Profile - Host
520_01	Production test firmware BLE test commands
610_07	BLE Multilink
610_06	BLE External Host

6.8.3 Fixes and Improvements since 10.0.1.28

Table 27: 10.0.1.32 Fixes and Improvements

Fix Number	Description
0031/01	Enabled –werror (warnings are reported as errors) compiler option and cleaned up warnings in SDK apps.
0028.08	Fixed BMS stability issues observed when more than 1 connection is active.
0028.10	Fixed support for PRODUCTION mode.
0028.11	Fixed waking up from button in SDK apps.
0016.07	Added temperature-triggered calibration in Radio driver.

6.8.4 Known Issues and Limitations of 10.0.1.32

Table 28: 10.0.1.32 Known Issues

Issue Number	Description
0031.01	Radio TX power is fixed to 0dB.



Issue Number	Description
0031.02	pxp_reporter application stability issues have been observed in stress tests.
0031.03	hogp_device application stability issues have been observed in stress tests.
0031.04	ble_multi_link application sometimes fail to report device disconnection.
0028.01	Charger configuration is only tested with wall plug adapters at room temperature.
0028.03	SUOTA stability issues have been observed with stress tests.
0028.04	Detaching from Eclipse Debugger is not always successful.
0028.05	SPI adapter creates unneeded clock pulses after byte read command.
0028.06	Parameter Update sometimes fails with LMP LL Response Timeout.
0028.07	Bond Management Service (BMS) example gives the same pin key after reset.
0028.09	TRNG is not used by the SDK for generating random numbers.
0016.04	Release files may include code copied from DA1468x SDK, not yet ported for DA1469x.
0016.05	Doxygen documentation still includes references to DA1468x SDK.
0016.09	Values returned by the GPADC driver are not calibrated.
0016.10	Watchpoint support for debugging is not included.



6.9 Version 10.0.1.28

Version 10.0.1.28 of SDK was released on March 22nd, 2018.

6.9.1 Overview

This was an engineering release of 10.0.1 SDK, which added support for the DA1469x device. It can be used for application development and functional testing. It is not yet fully evaluated and it cannot be used for testing final products.

Dialog will make every effort to maintain API compatibility. However, developed code may have to be ported to the official SDK release once that becomes available.

It included more BLE features, a set of crypto algorithms, and more low level drivers for peripherals on DA1469x, It also adds configuration of the integrated HW charger and system support for sleep mode. A detailed list of delivered features is given below.

6.9.2 New and Updated Features of 10.0.1.28

Table 29: 10.0.1.28 New Features

Feature Number	Description
110_01	LE Scatter net.
111_01	LE Secure Connection.
111_03	Enhanced Privacy 1.2.
120_32	WSS 1.0 : Weight Scale Service.
130_23	HRP 1.0: Heart Rate Profile.
130_43	WSP 1.0: Weight Scale Profile.
131_01	Apple Notification Center Service (ANCS) Client.
320_01	Clock and Power Management Low Level Driver.
320_02	Charger Low Level Driver.
321_02	AES Low Level Driver.
321_03	HASH Low Level Driver.
321_04	TRNG Low Level Driver.
326_06	USB Charger Low Level Support.
326_09	UART3 Low Level Driver.
328_06	ADC 1 Low Level Driver.
328_07	ERM Low Level Driver.
328_08	ADC 2 Low Level Driver.
400_02	FreeRTOS Tick-less Mode.
420_04	Security Framework (AES/ECC Crypto, TRNG).
420_05	Algo - Random Number Generation.
420_06	Algo - Hash Bytes.
420_07	Algo - Hash - Key Derivation.
420_08	Algo - Hash - HMAC Generation.
420_09	Algo - AES - Encrypt/Decrypt.
420_12	Algo – ECDH Generate/Verify Public/Session Key



Feature Number	Description	
450_03	System Management – Watchdog Service.	
450_04	System Management – Charger Service.	
460_02	Crypto Adapter.	

6.9.3 Fixes and Improvements since 10.0.1.16

Table 30: 10.0.1.28 Fixes and Improvements

Fix Number	Description	
0016.01	Added support for sleep mode. Demonstrated in pxp_reporter example.	
0016.02	Improved test coverage for the Bluetooth Framework.	
0016.03	Improved test coverage for drivers and SDK core.	
0016.08	Added implementation of BLE Secure Connections and Enhanced Privacy features.	
0016.06	Added support for multiple BLE connections.	

6.9.4 Known Issues and Limitations of 10.0.1.28

Table 31: 10.0.1.28 Known Issues

Issue Number	Description
0028.01	Charger configuration is only tested with wall plug adapters at room temperature.
0028.02	Radio TX power is fixed to 6dB.
0028.03	SUOTA stability issues have been observed with stress tests.
0028.04	Detaching from Eclipse Debugger is not always successful.
0028.05	SPI adapter creates unneeded clock pulses after byte read command.
0028.06	Parameter Update sometimes fails with LMP LL Response Timeout.
0028.07	Bond Management Service (BMS) example gives the same pin key after reset.
0028.08	BMS stability issues have been observed when more than 1 connections are active.
0028.09	TRNG is not used by the SDK for generating random numbers.
0028.10	PRODUCTION mode is not supported and should not be used.
0028.11	Waking up from button is not supported in SDK apps.
0016.04	Release files may include code copied from DA1468x SDK, not yet ported for DA1469x.
0016.05	Doxygen documentation still includes references to DA1468x SDK.
0016.07	Radio driver does not yet include calibration. Performance may be suboptimal.
0016.09	Values returned by the GPADC driver are not calibrated.
0016.10	Watchpoint support for debugging is not included.



6.10 Version 10.0.1.16

Version 10.0.1.16 of DA1469x SDK was released on February 7th, 2018

6.10.1 Overview

This was the first internal engineering release of 10.0.1 SDK that runs on the DA1469x devices. It should only be used for enabling silicon bring up and getting familiar with the SDK structure.

Please do not use this release for application development because APIs might change. Dialog will make every effort to maintain API compatibility. However, developed code may have to be ported to the official SDK release once that becomes available.

The DA1469x SDK is based on the Black Orca SDK architecture that supports DA1468x devices. Similar constructs with the DA1468x SW architecture include:

- i. FreeRTOS Operating System
- ii. Code execution in-place from QSPI Flash
- iii. BLE Framework that reuses the Adapter/Manager Layers and exposes the same API
- iv. Abstraction layer with low level drivers and adapters for peripheral devices

This release implements basic SDK architecture, including the BLE framework and support for the Sensor Node Controller. A detailed list of delivered features is given below.

6.10.2 New and Updated Features of 10.0.1.16

Table 32: 10.0.1.16 New Features

Feature Number	Description
110_02	L2CAP COC
110_03	Low Duty Cycle Advertising
111_02	LE Data Packet Length Extension
112_01	LE 2Mbps
114_02	Bluetooth Host subsystem can be updated as part of full application SUOTA
114_03	Bluetooth Controller subsystem can be updated as part of full application SUOTA
120_03	BAS 1.0: Battery Service
120_04	BCS 1.0: Body Composition Service
120_06	BMS 1.0: Bond Management Service
120_10	CTS 1.1: Current Time Service
120_11	DIS 1.1: Device Information Service
120_18	IAS 1.0: Immediate Alert Service
120_16	HRS 1.0: Heart Rate Service
120_20	LLS 1.0.1: Link Loss Service
120_28	ScPS 1.0: Scan Parameters Service
120_30	TPS 1.0: Tx Power Service
121_03	Dialog Debug Service 1.1
310_04	XiP (cached) from Flash
323_06	QSPI Flash Driver
323_10	NVMS partitions
325_01	Timers Low-Level Driver



Feature Number	Description	
325_02	RTC Low-Level Driver	
325_03	Watchdog Low-Level Driver	
326_01	GPIO Low-Level Driver	
326_02	SPI 1/2/3 Low-Level Driver	
326_03	I2C 1/2 Low-Level Driver	
326_04	UART 1/2 Low-Level Driver	
326_07	CMAC Mailbox driver included in BLE library	
326_08	LCD Low Level Driver	
328_02	White LED Low-Level Driver	
328_05	Sensor Node Controller Low-Level Driver	
400_01	FreeRTOS v9	
400_07	OS Abstraction Layer	
400_08	OS Abstraction Layer - Resource Management	
430_04	Software Upgrade over BLE (SUOTA)	
460_03	Flash Adapter	
460_04	LCD Adapter	
460_05	GPADC Adapter	
460_06	I2C Adapter	
460_07	NVMS Adapter	
460_11	SPI Adapter	
460_13	UART Adapter	
460_16	Sensor Node Controller Adapter	
510_02	Supported by GNU / GCC toolset	
510_03	Supported by JTAG debugger	
510_04	Supported from Eclipse-based IDE	
510_06	Sensor node controller programming	
530_01	Works with SmartSnippets Studio & Toolbox (version 2.0)	
610_02	PXP Reporter, including SUOTA example	
620_01	SUOTA example works with Dialog Android SUOTA App	

6.10.3 Known Issues and Limitations of 10.0.1.16

Table 33: 10.0.1.16 Known Issues

Issue Number	Description
0016.01	SDK does not support sleep mode, all projects run in always-active configuration.
0016.02	Bluetooth Framework has been only tested for basic BLE4.2 functionality.
0016.03	Evaluation is limited to functional testing of the demo applications delivered with the SDK.
0016.04	Release files may include code copied from DA1468x SDK, not yet ported for DA1469x.
0016.05	Doxygen documentation still includes references to DA1468x SDK.



DA1469x SDK

Issue Number	Description
0016.06	BLE stack may be confused if two or more connections are active. Use only one connection.
0016.07	Radio driver does not yet include calibration. Performance may be suboptimal.
0016.08	BLE Secure Connections and Enhanced Privacy features are not yet supported.
0016.09	Values returned by the GPADC driver are not calibrated.
0016.10	Watchpoint support for debugging is not included.

Appendix A Software Versioning Rules

This describes the software version numbers and does not apply to documentation version numbers (as found in the footer of this document).

Each software version number string consists of four numbers: MAJOR. BRANCH. MINOR. and BUILD.

#MAJOR: It is increased (by one only) if the project undergoes a major modification, for example major ROM changes. It usually changes only when the project sources undergo major restructuring affecting most of the repository. It is initialized at 1.

#BRANCH: Used in the case of concurrent projects that for special reasons need to be spun off the major repository. It corresponds to different versions of the repository code that have to be supported concurrently. In this case each branch number corresponds to a different GIT branch. The basic project has BRANCH id 0.

#MINOR: Odd numbers indicate Engineering (or Patch or Binary) versions, even numbers indicate Full release versions or Release Candidates of Full versions. Each Full release increases this number by one. After the Full release, the number is increased by one again. Therefore, Project releases correspond to release numbers like 2.0.1.xxx, 2.0.2.xxx. etc. The #MINOR number is initialized at 1.

#BUILD: The # BUILD number increases by one at every repository update and thus indicates the total number of changes since repository initialization. The BUILD number is initialized at 1.



DA1469x SDK

Document Revision History

This section summarizes the changes made to this document and not to the Software that this document describes.

Revision	Date	Description	
11	27-Sep-2019	Full Release 10.0.6.90	
- Added OTP C	Change details: - Added OTP CS settings for XTAL Trim & BD Address - Split Issues and Limitations in two tables		
10	02-Aug-2019	Full Release 10.0.6.88	
9	24-Apr-2019	Added workaround for errata issue 304. Updated Disaclaimer Text. Full release 10.0.4.66.2	
8	17-Apr-2019	Remove mistaken reference to Cycling Power profile. Code Labeling fixes. Full release 10.0.4.66.1	
7	22-Feb-2019	Launch of DA1469x Family of Devices. Full release 10.0.4.66	
6	14-Jan-2019	Product Development Ready. Full release 10.0.2.60	
5	07-Dec-2018	Product Development Ready. Engineering 10.0.1.52	
4	28-Sept-2018	Improved Maturity. Engineering 10.0.1.39	
3	25-May-2018	Migrate to FreeRTOS v10. Engineering 10.0.1.32	
2	22-March-2018	Updated with more features. Engineering 10.0.1.28	
1	07-Febr-2018	Initial version. Engineering release 10.0.1.16	



Status Definitions

Status	Definition
DRAFT	The content of this document is under review and subject to formal approval, which may result in modifications or additions.
APPROVED or unmarked	The content of this document has been approved for publication.

Disclaimer

Unless otherwise agreed in writing, the Dialog Semiconductor products (and any associated software) referred to in this document are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of a Dialog Semiconductor product (or associated software) can reasonably be expected to result in personal injury, death or severe property or environmental damage. Dialog Semiconductor and its suppliers accept no liability for inclusion and/or use of Dialog Semiconductor products (and any associated software) in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Information in this document is believed to be accurate and reliable. However, Dialog Semiconductor does not give any representations or warranties, express or implied, as to the accuracy or completeness of such information. Dialog Semiconductor furthermore takes no responsibility whatsoever for the content in this document if provided by any information source outside of Dialog Semiconductor.

Dialog Semiconductor reserves the right to change without notice the information published in this document, including, without limitation, the specification and the design of the related semiconductor products, software and applications. Notwithstanding the foregoing, for any automotive grade version of the device, Dialog Semiconductor reserves the right to change the information published in this document, including, without limitation, the specification and the design of the related semiconductor products, software and applications, in accordance with its standard automotive change notification process.

Applications, software, and semiconductor products described in this document are for illustrative purposes only. Dialog Semiconductor makes no representation or warranty that such applications, software and semiconductor products will be suitable for the specified use without further testing or modification. Unless otherwise agreed in writing, such testing or modification is the sole responsibility of the customer and Dialog Semiconductor excludes all liability in this respect.

Nothing in this document may be construed as a license for customer to use the Dialog Semiconductor products, software and applications referred to in this document. Such license must be separately sought by customer with Dialog Semiconductor.

All use of Dialog Semiconductor products, software and applications referred to in this document is subject to Dialog Semiconductor's Standard Terms and Conditions of Sale, available on the company website (www.dialog-semiconductor.com) unless otherwise stated.

Dialog, Dialog Semiconductor and the Dialog logo are trademarks of Dialog Semiconductor Plc or its subsidiaries. All other product or service names and marks are the property of their respective owners.

© 2019 Dialog Semiconductor. All rights reserved.

RoHS Compliance

Dialog Semiconductor's suppliers certify that its products are in compliance with the requirements of Directive 2011/65/EU of the European Parliament on the restriction of the use of certain hazardous substances in electrical and electronic equipment. RoHS certificates from our suppliers are available on request.

Contacting Dialog Semiconductor

United Kingdom (Headquarters)

Dialog Semiconductor (UK) LTD Phone: +44 1793 757700

Germany

Dialog Semiconductor GmbH Phone: +49 7021 805-0

The Netherlands

Dialog Semiconductor B.V. Phone: +31 73 640 8822

enquiry@diasemi.com

North America

Dialog Semiconductor Inc. Phone: +1 408 845 8500

Japan

Dialog Semiconductor K. K. Phone: +81 3 5769 5100

Taiwan

Dialog Semiconductor Taiwan Phone: +886 281 786 222

Web site:

www.dialog-semiconductor.com

Hong Kong

Dialog Semiconductor Hong Kong Phone: +852 2607 4271

Korea

Dialog Semiconductor Korea Phone: +82 2 3469 8200 China (Shenzhen)

Dialog Semiconductor China Phone: +86 755 2981 3669

China (Shanghai)

Dialog Semiconductor China Phone: +86 21 5424 9058